

PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | |
|---|---|---------------|----------------|---------------------|------------|-----------------|------------|---------------|------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Masaomi KAMAKURA</td> <td>08/28/2009</td> </tr> <tr> <td>Toshio KUMAMOTO</td> <td>08/28/2009</td> </tr> <tr> <td>Takashi OKUDA</td> <td>08/28/2009</td> </tr> </tbody> </table> | | Name | Execution Date | Masaomi KAMAKURA | 08/28/2009 | Toshio KUMAMOTO | 08/28/2009 | Takashi OKUDA | 08/28/2009 |
| Name | Execution Date | | | | | | | | |
| Masaomi KAMAKURA | 08/28/2009 | | | | | | | | |
| Toshio KUMAMOTO | 08/28/2009 | | | | | | | | |
| Takashi OKUDA | 08/28/2009 | | | | | | | | |
| RECEIVING PARTY DATA | | | | | | | | | |
| Name: | RENESAS TECHNOLOGY CORP. | | | | | | | | |
| Street Address: | 6-2, Otemachi 2-chome, Chiyoda-ku, | | | | | | | | |
| City: | Tokyo | | | | | | | | |
| State/Country: | JAPAN | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12570650</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 12570650 | | | | |
| Property Type | Number | | | | | | | | |
| Application Number: | 12570650 | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | |
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| ATTORNEY DOCKET NUMBER: | 067237-0559 | | | | | | | | |
| NAME OF SUBMITTER: | Stephen A. Becker | | | | | | | | |
| Total Attachments: 2 source=0672370559assignmenttransmittal#page1.tif source=0672370559assignment#page1.tif | | | | | | | | | |

CH \$40.00 12570650

RECORDATION FORM COVER SHEET

Docket No.: 067237-0559

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Masaomi KAMAKURA, Toshio KUMAMOTO, Takashi OKUDA

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: **RENESAS TECHNOLOGY CORP.**

Internal Address:

Address: **6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, JAPAN**

Additional name(s) & address(es) attached? Yes No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **August 28, 2009**

- Assignment Merger
- Security Agreement Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other

4. Application or patent number(s):

A. Patent Application No(s).

This document is being filed together with a new application.

B. Patent No(s).

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: **MCDERMOTT WILL & EMERY LLP**

Internal Address:

Street Address: **600 13th Street, N.W.**

City: **Washington** State: **D. C.** Zip: **20005-3096**

Phone Number: **202.756.8000**

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6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information:

- a. Credit Card Last 4 Numbers _____
Expiration Date _____
- b. Deposit Account Number 500417
Authorized User Name _____

9. Signature.

Stephen A. Becker 26,527



September 30, 2009

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents: **2**

ASSIGNMENT

(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A SEMICONDUCTOR DEVICE HAVING RESISTORS WITH A BIASED SUBSTRATE VOLTAGE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.

Signed on the date(s) indicated aside our signatures:

| | INVENTOR(S) (発明者フルネームサイン) | Date Signed (署名日) |
|-----|--|-----------------------|
| 1) | <u>Masaomi Kamakura</u> Masaomi KAMAKURA | <u>28/August/2009</u> |
| 2) | <u>Toshio Kumamoto</u> Toshio KUMAMOTO | <u>28/August/2009</u> |
| 3) | <u>Takashi Okuda</u> Takashi OKUDA | <u>28/August/2009</u> |
| 4) | _____ | _____ |
| 5) | _____ | _____ |
| 6) | _____ | _____ |
| 7) | _____ | _____ |
| 8) | _____ | _____ |
| 9) | _____ | _____ |
| 10) | _____ | _____ |

PATENT